



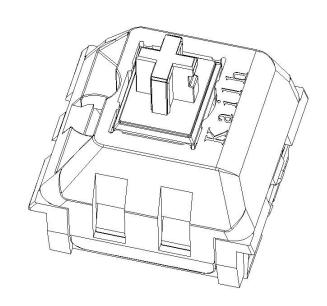


## **Document Number:**

KH-PS1608-04

# 产品规格书

Product Specification



| <u>P/N:</u>  | -   |                                   | Title:             |                  |                   |
|--------------|-----|-----------------------------------|--------------------|------------------|-------------------|
| CPG151101D13 |     |                                   | CPG1               | 511 Keyboar      | d Switch          |
| Rev.         | ECN | Release and Revision Description: | Prepared By /Date: | Checked By/Date: | Approved By/Date: |
| A            |     | New releasing 初版发行                | 汤佳 2017.09.18      | 胡远锋 2017.09.18   | 王锋 2017.09.18     |
|              |     |                                   |                    |                  |                   |
|              |     |                                   |                    |                  |                   |
|              |     |                                   |                    |                  |                   |
|              |     |                                   |                    |                  |                   |



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#### 1. Scope/范围:

This Product Specification covers the requirement of Mechanical Keyboard switch on product performance, test methods and quality assurance provisions.

本规格书内容涵盖机械键盘开关产品的要求,包括性能指标、测试方法及质量保证方面等。

#### Product Application/产品应用:

Mainly applied on computer keyboards, cash registers, industrial equipment and Man-Machine interface.

主要适用于电脑键盘,收银机、工业设备和人机界面。

#### Technology Parameters/技术参数

Ambient Humidity 工作湿度: 45~85% R.H.;

Operating Temperature Range 使用温度范围: -10℃~+70℃: Storage Temperature Range 保存温度范围: -20℃~+70℃;

Suggested storage period 贮存期限: about 6 months 最多 6 个月

Require the tin part on the switch terminals should keep good after storage guarantee date 要求贮存期后开关端子部分上锡仍然良好。

Normal Condition:

Ambient temperature 环境温度: 20+2°C

Relative humidity 相对湿度: 65% ± 5% R.H.; Air pressure 气压: 86~101KPa:

#### Ratings/额定性能要求

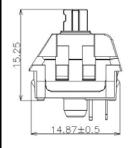
Rating 额定负荷:

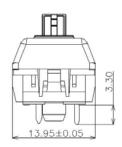
Insulation Resistance 绝缘电阻: Withstand Voltage 耐电压: Mechanical Life 机械寿命: Profile Dimensions /外形尺寸

12V AC/DC max.2V DC min. 10mA AC/DC max.10 µ A DC min:

 $\geq$ 100M $\Omega$ /DC 500V: 100V AC 1 Minute: 70,000,000 Cycles.









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### 5. Electrical Performance/电气性能

| Item<br>项目 | Description<br>项目描述                          | Test Condition 测试条件   | Requirement 规格要求  |
|------------|--|---|---|
| 6.1        | Contact<br>Resistance<br>接触电阻                | Static load: (Operation force)x2, which is applied on the center of Switch stem. 静态负载:动作力的 2 倍,施加在手柄中心.  Measurement tool: Contact resistance Meter. 测量工具:微电流接触电阻计(1KHz, 20mV,5~50mA)  在低电流(≤100mA)条件下测试.  Measured at low curr nt (100mA or less). | 100mΩ Max<br>100mΩ以下  |
| 6.2        | Insulation<br>Resistance<br>绝缘电阻             | Apply a Voltage of DC 500 V for 1 minute, according to the below method. (1) Between terminals. (2) Between terminal and Body. 输入 500V DC 电压 1 分钟,按如下接触方法测试: (1) 端子与端子之间. (2) 端子与外壳之间.  | 100MΩ Min<br>100 兆欧以上   |
| .3         | Dielectric<br>withstanding<br>voltage<br>耐电压 | Apply a Voltage of AC100 V (50~60Hz) for 1 minute, according to the below method. (1) Between terminals. (2) Between terminal and Body. 输入 100V AC 电压 1 分钟, 按如下接触方法测试: (1) 端子与端子之间. (2) 端子与外壳之间.  | No evidence of breakdown<br>无瞬断、击穿等破坏.  |
| 6.4        | Bouncing<br>触点抖动                             | Operation speed: 3~4 times/s<br>操作速度: 每秒 3~4 次<br>Oscillo scope 示波器<br>Switch Bouncing Test Circuit 抖动测定回路.   | Before Life cycle:<br>On:5ms MAX,5 毫秒以下<br>Off: 5ms MAX,5 毫秒以下<br>After Life cycle:<br>On:10ms MAX,10 毫秒以下<br>Off: 10ms MAX,10 毫秒以下 |



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#### Mechanical Performance/机械性能

| 6. Me Item 项目 | Description<br>项目描述          | ormance/机械性能 Test Condition 测试条件  | Requirement 规格要求       |
|---------------|------------------------------|---|------------------------|
| 7.1           | Load<br>Curve<br>荷重曲线        | Place the vertical direction of switch operation and gradually increase the load applied to the center of the stem until it stop. 开关的动作方向为垂直放置,向手柄中心逐渐施加负荷直到停止.  Force-Travel-diagram 操作力-行程-图解  120 100 100 100 100 100 100 100 100 10 | See page 11<br>见第 11 页 |
| 7.2           | Loading<br>parameter<br>荷重参数 | Place the vertical direction of switch operation and gradually increase the load applied to the center of the stem until it stop. 开关的动作方向为垂直放置,向手柄中心逐渐施加负荷直到停止.   | See page 11<br>见第 11 页 |



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| 7.3 | Static<br>Strength<br>静止强度          | A static load of 3kgf shall be applied in the direction of button operation for a period of 60 seconds. 在手柄动作方向施加 3kgf 的静负荷 60 秒, 然后测试参数.  | No damag<br>(Electrical)<br>And mech<br>电气和机械  | )<br>anical)   |               |
|-----|-------------------------------------|--|--|--|---------------|
| 7.4 | Stem Pull<br>Strength<br>手柄拉拔强<br>度 | Break by a pull force applied opposite to the direction of stem operation. 在推柄动作方向反向垂直施加拉力,使其破坏的程度.  | 5kgf   | Min  |               |
| 7.5 | Shock<br>机械冲击                       | Measured by according to the below condition:  (1) Acceleration: 80g 加速度  (2) Cycles of test:3 cycles each in 6 directions, for a total of 18 cycles. 试验次数: 每个方向 3 次, 6 个方向共 18 次.   | Shall meet<br>7.2.<br>满足 6,7   |  | ·             |
| 7.6 | Life Test<br>寿命测试                   | 1) D.C.12V 10mA resistance load D.C 12V 10mA 电阻负荷 2) Operation speed: 5-6 times / s 动作速度: 5-6 次/ 秒 3) Push force: 150gf 按力: 150gf 5) Push travel: 4.0mm 按压行程: 4.0mm 6) Operation number: 70,000,000cycles 动作次数: 70,000,000 次 | Contact re 1000 m Ω 接触电阻:<br>Bouncing:<br>触点抖动:<br>Operation variation ra 30%<br>操作力的多值的±30% | Max<br>1000 毫欧<br>10ms Ma<br>10 毫秒以<br>force:<br>ate within<br>变化范围在 | ax<br>以下<br>土 |



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#### 7. Environmental Performance/环境性能

| Item<br>项目 | Description<br>项目描述            | Test Condition 测试条件   | Requirement 规格要求   |
|------------|--------------------------------|---|--|
| 8.1        | Cold test<br>耐寒性               | <ul> <li>(1) Temperature: -20±2℃</li> <li>温度: -20±2℃</li> <li>(2) Duration of test: 48h</li> <li>持续时间: 48 小时</li> <li>(3) Take off a drop water 去掉水珠</li> <li>(4) Standard conditions after test: 1h</li> <li>试验后的放置条件: 1 小时</li> </ul> | Contact resistance: 200m Ω Max Shall meet: No. 6.2 to 6.4 No. 7.1 to 7.2 接触电阻 200m Ω以下 满足: No. 6.2 to 6.4 No. 7.1 to 7.2 |
| 8.2        | Heat test<br>耐热性               | <ul> <li>(1) Temperature: 70±2℃</li> <li>温度: 70±2℃</li> <li>(2) Duration of test: 48h</li> <li>持续时间: 48 小时</li> <li>(3) Take off a drop water 去掉水珠</li> <li>(4) Standard conditions after test: 1h</li> <li>试验后的放置条件: 1 小时</li> </ul>   | Contact resistance: 200m Ω Max Shall meet: No. 6.2 to 6.4 No. 7.1 to 7.2 接触电阻 200m Ω以下 满足: No. 6.2 to 6.4 No. 7.1 to 7.2 |
| 8.3        | Temperature<br>cycle<br>温度循环   | (1) Test cycles: 5 cycles   | Contact resistance: 200m Ω Max Shall meet: No. 6.2 to 6.4 No. 7.1 to 7.2 接触电阻 200m Ω以下 满足: No. 6.2 to 6.4 No. 7.1 to 7.2 |
| 8.4        | Soldering<br>heat test<br>耐焊接热 | Soldering area: T/2 of PWB thickness. (PWB: T=1.6mm)<br>焊接面积: 印刷基板的 1/2 厚度处<br>Soldering temperature: 260±5℃<br>Soldering time: 5±0.5s<br>焊接温度: 260±5℃<br>焊接时间: 5±0.5 秒   | Appearance:<br>No abnormality.<br>外观无异常  |



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| Щ_ |   |                    |   | <u> </u>  |
|----|---|--------------------|---|---|
|    | Solder ability 可焊性 For the product of T/H according to below condition: area of ir portion s by solder  |                    | At least 95% of surface area of immersed portion shall be covered by solder. 侵焊面积大于 95%以上.  |   |
|    | (1) Temperature: 60±2℃ 温度: 60±2℃ (2) relative humidity: 90~95% R.H. 相对湿度:90~95% R.H. (3) Duration of test: 48h 持续时间: 48 小时 (4) Take off a drop water 去掉水珠 (5) Standard conditions after test: 1h 试验后的放置条件: 1 小时 |                    | Contact resistance:<br>200m Ω Max<br>Shall meet:<br>No. 6.2 to 6.4<br>No. 7.1 to 7.2<br>接触电阻 200m Ω以下<br>满足:<br>No. 6.2 to 6.4<br>No. 7.1 to 7.2  |   |
|    | 8.7   | Salt Spray<br>盐雾测试 | Apply the following environment to tes 根据下列条件进行测试: (1) Temperature: 35±5℃ 温度: 35±5℃; (2) Salt water density: 5±1% 盐水浓度: 5±1%; (3) Duration: 12hours 持续时间: 12 小时; (4) After test, the salt deposit shall be removed by running water. 实验后将盐沉积物用水冲掉 | Appearance: No corrosion spot, no crack, no base plate naked. 外观: 无腐蚀点, 无裂纹, 无裸露基材.  Contact Resistance: 200 m Ω Max 接触电阻: 200 毫欧以下 |



8.8

Withstand

K<sub>2</sub>S 硫化测试

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Apply the following environment to test: 根据下列条件进行测试

(1) Temperature: 35±5℃温度: 35±5℃

(2) K<sub>2</sub>S Density: 2%; 硫化钾浓度: 2%

(3) Duration: 2 minute. 持续时间: 2 分钟 Appearance: No corrosion spot, no crack, no base plate naked.

外观:无腐蚀点,无裂纹, 无裸露基材.

Contact Resistance: 1000 m Ω Max 接触电阻: 1000 毫欧以 下

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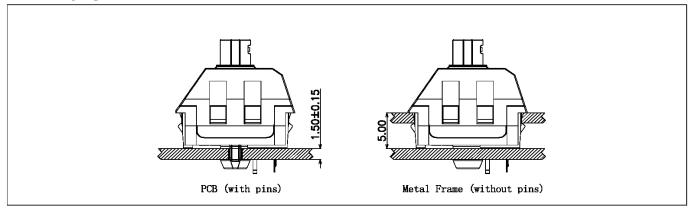
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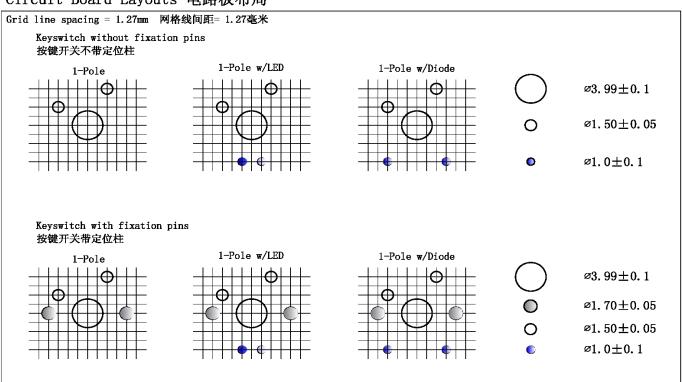
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## 8. Recommended PCB Layout 推荐的 PCB 安装焊盘规格

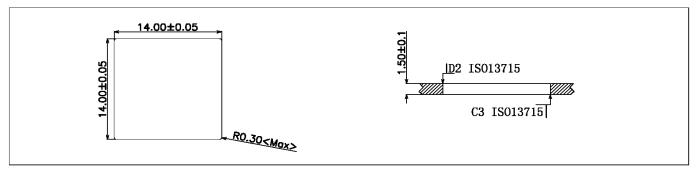
Mounting Options 安装选项



#### Circuit Board Layouts 电路板布局



#### Metal Frame Cutout Dimensions





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#### 9. Loading Parameter (FP/OP/PT/OF/OT /MD/CF/RF/TT) Specification 荷重参数规格:

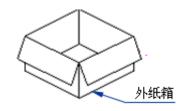
| Parameter | Unit | Specification   | Remark |
|-----------|------|-----------------|--------|
| FP(自由行程)  | mm   | 15.25±0.2       |        |
| OP(动作行程)  | mm   | 13.35±0.6       |        |
| PT(导通行程)  | mm   | $1.90 \pm 0.40$ |        |
| OF(操作力)   | gf   | 50±10           |        |
| OT(过行程)   | mm   | 1.3             | Min    |
| MD(差动行程)  | mm   | 0.6             | Max    |
| CF (触感力)  | gf   | 60±10           |        |
| RF(回弹力)   | gf   | 15              | Min    |
| TT(总行程)   | mm   | 4.00 +0 -0.4    |        |

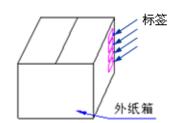
#### 11. Packaging 包装

Packaging type: Tray, 1000Pcs/Tray, 4000Pcs/Carton.

包装方式: Tray 盘,1000Pcs/盘,4000Pcs/箱.







#### 12.Precaution 注意事项

12.1 Immersion Soldering condition 浸焊条件

| ITEM                  | CONDITION  |
|-----------------------|--|
| 项目                    | 条件   |
| Preheat temperature   | 110℃ Max (Ambient temperature of soldering surface of P.W.B) |
| 预热温度                  | 110℃以下(印刷基板焊锡面周围的温度)   |
| Preheat time 预热时间     | 60s, Max 60 秒以内  |
| Area of flux          | 1/2 Max of PWB Thickness                                     |
| 助焊剂面积                 | 印刷基板厚度的 1/2 以内   |
| Temperature of solder | 260±5℃   |
| 焊锡温度                  | 260±5℃   |
| Time of immersion     | Within 5s  |
| 浸焊时间                  | 5 秒以内  |
| Number of soldering   | 2time Max (But should down heat of the first soldering)      |
| 焊接次数                  | 2 次以内  |
| Printed wiring board  | Single side copper-clad laminates                            |
| 印刷基板                  | 单面铜箔   |

- (1) After switches were soldered, please be careful not to clean switches with solvent 开关浸焊后,注意不要用溶剂清洗.
- (2) Under the condition of using soldering iron, soldering temperature shall be 350 ℃ max within 3 sec.



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在使用铬铁的情况下,焊锡温度应在350℃以下,焊接时间3秒以内.

#### 12.2 Notes 注意点

- (1) Please be cautious not to give excessive static load or shock to switches.
  - 注意不要施加超负荷的压力或晃动开关.
  - (2) Please be careful not to stack up P. W. B. after switches were soldered. 开关焊接以后,印刷基板注意不要叠放.
  - (3) Preservation under high temperature and high humidity or corrosive gas should be avoided Especially. When you need to preserve for a long period, do not open the carton. 保管时尤其应注意避开高湿高温和有腐蚀性气体的环境.如需长时间保存,请不要打开包装箱.
  - (4) Products meet the ROHS & REACH environmental management substances control standards 产品满足 ROHS & REACH 环境管理物质管制标准